

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

- **Package:** DO-214AA (SMB)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■Maximum Ratings (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS3AB	GS3BB	GS3DB	GS3GB	GS3JB	GS3KB	GS3MB
Device marking code			GS3AB	GS3BB	GS3DB	GS3GB	GS3JB	GS3KB	GS3MB
Maximum Repetitive peak reverse voltage	V _{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V _{DC}	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	I _O	A	3.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T _j =25°C	I _{FSM}	A	100						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T _j =25°C			200						
Current squared time @1ms≤t≤8.3ms T _j =25°C	I ² t	A ² s	41.5						
Storage temperature	T _{stg}	°C	-55 ~ +150						
Junction temperature	T _j	°C	-55 ~ +150						

■Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GS3AB	GS3BB	GS3DB	GS3GB	GS3JB	GS3KB	GS3MB
Maximum instantaneous forward voltage	V _F	V	I _{FM} =3.0A	1.1						
Maximum DC reverse current at rated DC blocking voltage	I _R	μA	T _j =25°C	5						
			T _j =125°C	100						
Typical junction capacitance	C _j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	25						

■ **Thermal Characteristics** ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS3AB	GS3BB	GS3DB	GS3GB	GS3JB	GS3KB	GS3MB
Typical Thermal Resistance	$R_{\theta J-A}^{(1)}$	$^{\circ}\text{C/W}$	65						
	$R_{\theta J-L}^{(1)}$		22						
	$R_{\theta J-C}^{(1)}$		18						

Note:
(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

■ **Characteristics (Typical)**

FIG.1: I_o - T_L Curve

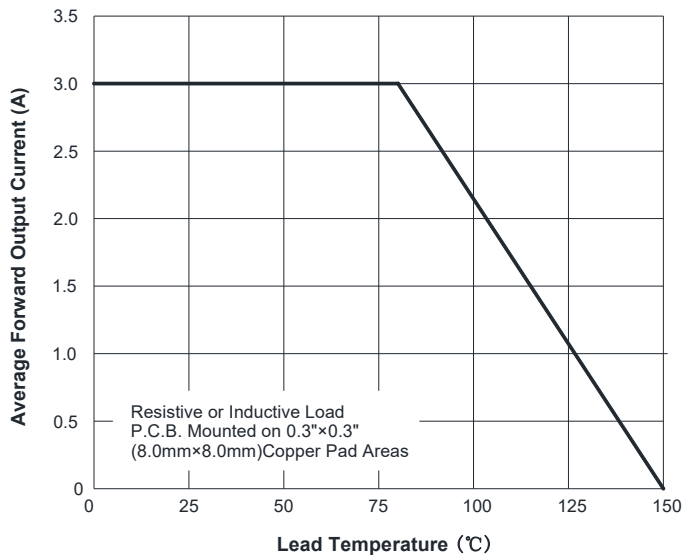


FIG.2: Forward Surge Current Capability

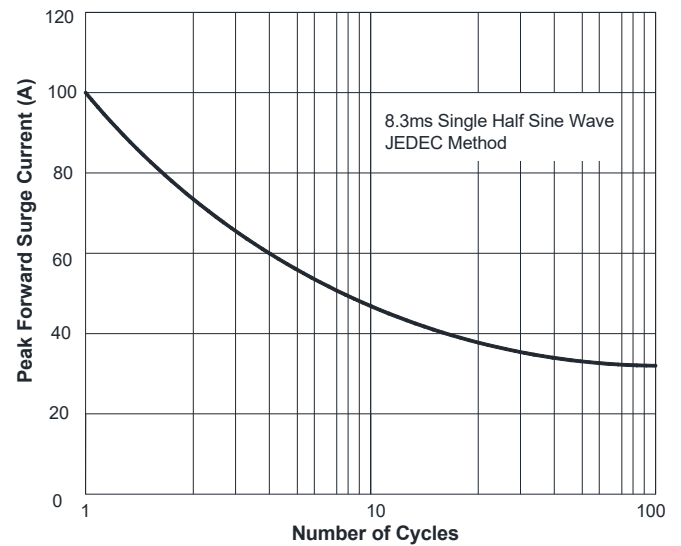


FIG.3: Typical Forward Voltage

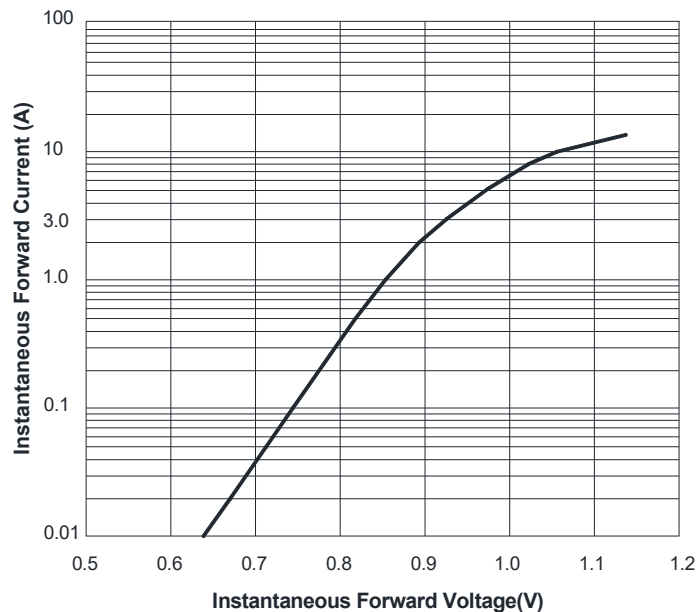
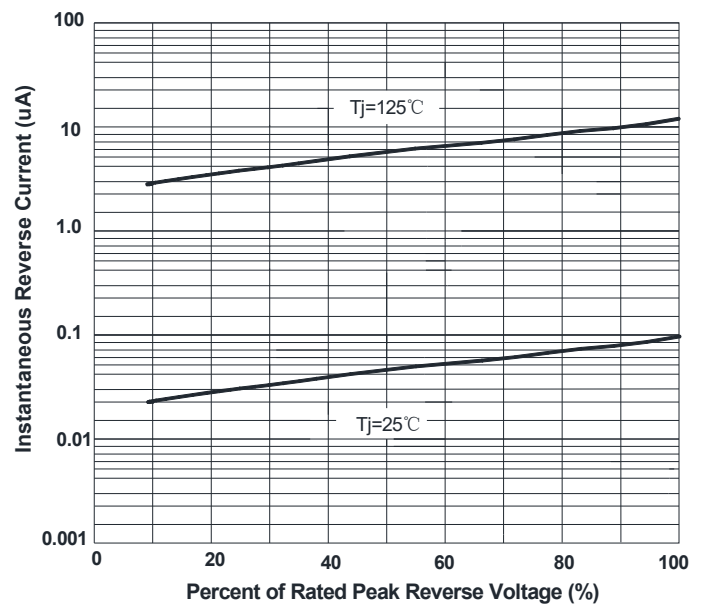


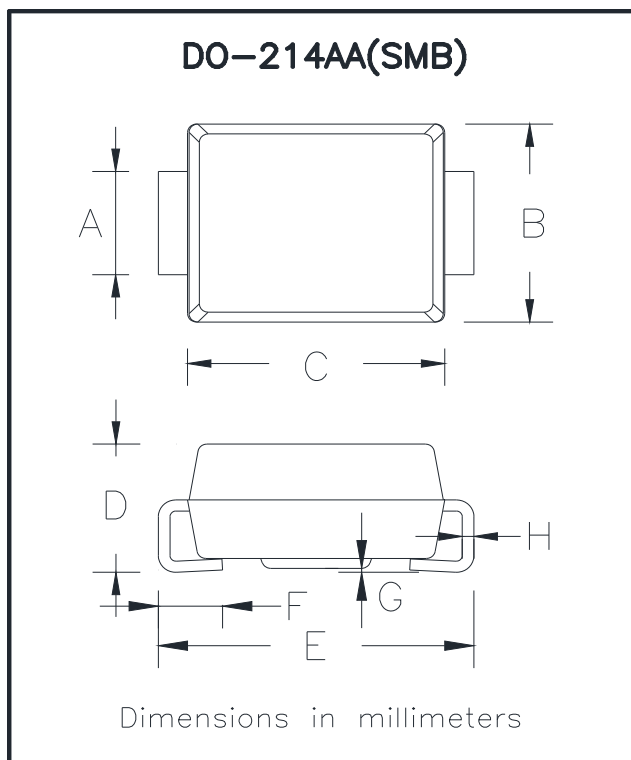
FIG.4: Typical Reverse Characteristics



■ Ordering Information (Example)

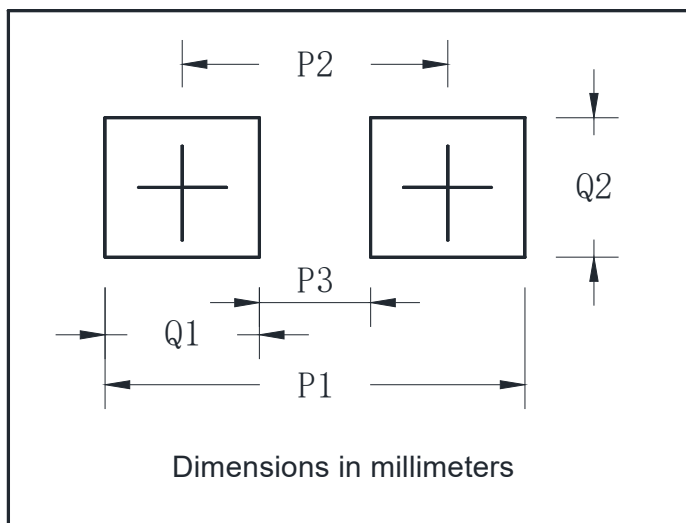
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GS3AB-GS3MB	F1	Approximate 0.096	3000	/	48000	13" reel
GS3AB-GS3MB	F2	Approximate 0.096	750	6000	24000	7" reel
GS3AB-GS3MB	F3	Approximate 0.096	500	4000	16000	7" reel

■ Outline Dimensions



DO-214AA(SMB)		
Dim	Min	Max
A	1.85	2.15
B	3.30	3.94
C	4.05	4.75
D	1.99	2.61
E	5.21	5.59
F	0.90	1.41
G	0.05	0.20
H	0.15	0.31

■ Suggested pad layout



DO-214AA(SMB)	
Dim	Millimeters
P1	6.8
P2	4.3
P3	1.8
Q1	2.5
Q2	2.3